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## 5380635-2 Product Details



5380635-2

Discrete Sockets



#### Product Highlights:

- Mini-Spring Socket Product Line
- · Board-to-Board, Wire-to-Board
- . Applies To Wire/Cable, Applies To Printed Circuit Board
- Contact Rated Current = 7.5 A
- Wire/Cable Size = .162 .653 mm²

View all Features

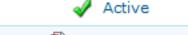
#### Quick Links-

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- Pricing & Availability
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TE Internal Number: 5380635-2













#### Documentation & Additional Information

#### Product Drawings:

REUSABLE COMPONENT RECEPTACLE (PDF, English)

#### Catalog Pages/Data Sheets:

None Available

#### Product Specifications:

None Available

#### Application Specifications:

None Available

#### Instruction Sheets:

None Available

#### CAD Files: (CAD Format & Compression Information)

- 2D Drawing (DXF, Version A)
- 3D Model (IGES, Version A)
- 3D Model (STEP, Version A)

## Additional Information:

Product Line Information

#### Related Products:

Tooling



#### Product Features (Please use the Product Drawing for all design activity)

## Product Type Features:

- Product Line = Mini-Spring Socket
- Socket Length (mm [in]) = 6.45 [0.254]
- Sleeve Style = Open Bottom
- Sealant = Without
- Wire/Cable Type = Discrete Wire
- Termination Method to Wire/Cable = Solder
- Termination Method to PC Board = Through Hole Press Fit
- Product Series = 5

Electrical Characteristics:

- Sleeve Material = Copper
- Profile = Zero

## Contact Features:

List all Documents

- Contact Spring Plating = Gold (30)
- Contact Plating, Mating Area, Material = Gold (30)
- Contact Plating, Mating Area, Thickness (μm [μin]) = 0.00076 [0.03]
- Contact Type = Socket
- Contact Base Material = Beryllium Copper

## Industry Standards:

- Government/Industry Qualification = No
- RoHS/ELV Compliance = RoHS compliant, ELV compliant
- Lead Free Solder Processes = Wave solder capable to 240°C, Wave solder capable to 260°C, Wave solder capable to 265°C, Reflow solder capable to 245°C, Reflow solder capable to 260°C, Pin-in-Paste capable to 245°C, Pin-in-Paste capable to 260°C
- RoHS/ELV Compliance History = Always was RoHS compliant

#### **Termination Features:** Environmental: Wire/Cable Size (mm²) = 0.162 - 0.653 Operating Temperature (°C [°F]) = -65 - +126 [-85 - +258]

Wire/Cable Size (AWG) = 19 - 25

Contact - Rated Current (A) = 7.5

Insertion Method = Hand/Semi-Automatic

## Dimensions:

- Recommended Hole Size (mm [in]) = 2.26 [0.089]
- PCB Thickness, Recommended (mm [in]) = 0.79 3.18 [0.031 -0.125]

## Body Features:

- Mating Pin Dia. Range (mm [in]) = 0.46 1.02 [0.018 0.040]
- Sleeve Material Plating = Tin
- Wire Type = Solid
- Spring Material = Beryllium Copper

# Conditions for Usage:

Applies To = Wire/Cable, Printed Circuit Board

## Operation/Application:

- Application Use = Board-to-Board, Wire-to-Board
- Contact Transmits (Typical Application) = Signal (Data)/Power
- Application = Testing/Reusable

## Packaging Features:

- Packaging Method = Loose Piece
- Packaging Quantity = 2,000/Bag

## Other:

Brand = AMP

## Corporate Information

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